

Aurotech® G-Bond 2

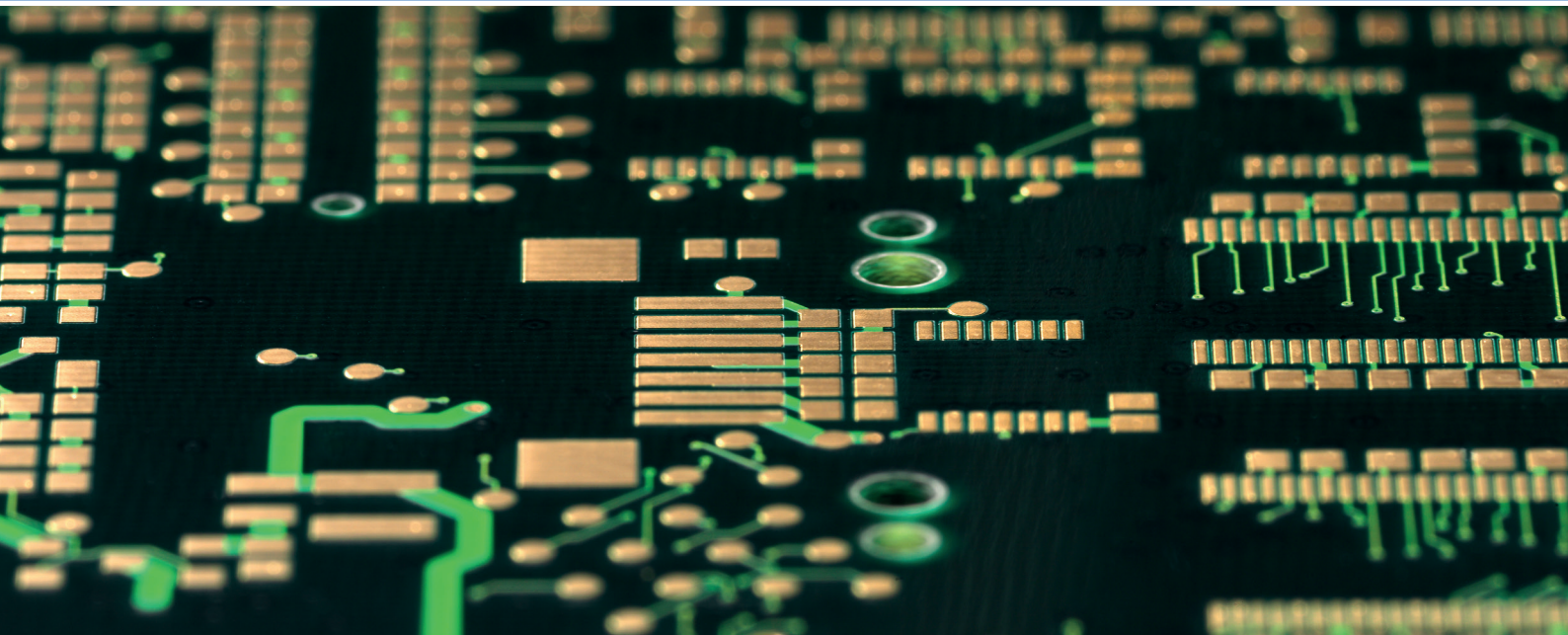
Corrosion free ENIG, ENEPIG and EPAG



Electronics

Final finishing technology

atotech.com



Aurotech® G-Bond 2 is the next generation mixed reaction gold for ENIG, ENEPIG and EPAG

The corrosion free solution for ENIG and ENEPIG

Aurotech® G-Bond 2 is the new gold electrolyte to fulfill all standards for ENIG, ENEPIG and EPAG with highest reliability. The process offers the benefits of a low gold content while achieving excellent thickness distribution at the same time. Both contribute to significant cost savings by reduced drag out losses and tightened thickness ranges. The production proven automated dosing system, which is complementary to Aurotech® G-Bond 2, ensures easy handling and consistent process conditions in work and idle times.

Features and benefits

- Low gold content of 0.5 g/l
- High bath stability, no risk for plate out
- 100% fulfillment of IPC 4552 corrosion requirements
- Excellent thickness distribution of CoV 5% and lower
- Reduced process cost by low gold content and thickness distribution
- Automated dosing system available

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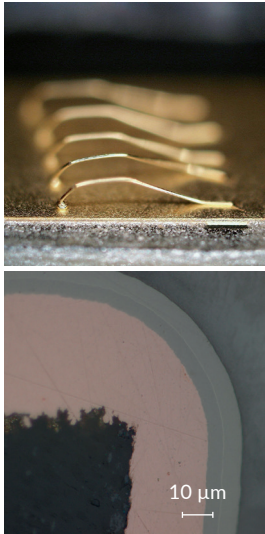


Figure 1-2:
Gold wire bondable finish
with ENEPIG
No corrosion with ENIG
and ENEPIG

Aurotech® G-Bond 2 fulfills IPC 4552 requirements

Atotech's latest gold bath development operates with a low gold content. At the same time it can achieve excellent thickness distribution. These major benefits lead to significant cost reduction. The new gold bath also fulfills all IPC 4552 requirements.

Building on the experience with the mass production proven predecessor Aurotech® G-Bond for ENEPIG, this new electrolyte offers exceptional bath stability for ENIG, ENEPIG and EPAG processing.

Complementary dosing unit for easy process control

In order to ease the handling and maintenance of the process, Atotech offers complementary dosing equipment which allows a continuous replenishment and ensures constant bath and plating conditions in production environment.

Operating parameters

- Gold content: 0.5 g/l (0.3 – 0.7)
- Plating temperature: 78 – 83 °C
- pH of the electrolyte: 7.8 – 8.2
- Plating rate: ENIG: 80 nm/10 min, ENEPIG 50 nm/10 min

